

TECHNICAL DATA SHEET

W112800

Revision date: 2/27/2025

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
 262-253-5900 FAX 262-253-5919

DESCRIPTION:

Resinlab® W112800 is a two part electronics grade low viscosity solvent based epoxy coating designed for protecting various materials from exposure to harsh chemical environments. It cures at room temperature to a tough, semi-rigid polymer. It has good wetting and adhesion to most surfaces and is free flowing to penetrate voids and give good air release and a smooth high gloss surface. It has very good resistance to water, acids and bases and most organic solvents.

W112800 was formulated to a 2A:1B volume mix ratio for small batch mixing. It will reach handle cure at room temperature within 24 hours, full cure for maximum thermal and chemical resistance requires 7 to 10 days. Cure time can be accelerated by the application of heat after product has gelled. Times and temperatures such as 2.5 hours at 57 °C, 2 hours at 65 °C or 30 minutes at 100 °C are typical for most applications. Heat should be applied after all solvent has been allowed to evaporate.

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Clear to Amber	Visual
Mix Ratio	Part A to Part B	Calculated
Mix Ratio by weight	2.23 to 1	
Mix Ratio by volume	2 to 1	
Cure Schedule	7-10 days @ 25 °C 2.5 hrs @ 57 °C 2 hrs @ 65 °C 30 min @ 100 °C	
Viscosity - Part A	130 cP	TA HR20 Rheometer 25mm parallel plate @ 1/s DCV6100723
Viscosity - Part B	350 cP	
Viscosity - Mixed	180 cP	
Specific Gravity - Part A	1.02	Calculated
Specific Gravity - Part B	0.91	
Specific Gravity - Mixed	0.98	
Pot Life - Cup and Stick	16 hours (200 g sample)	453560822627/Visual
Percent Solids	60 – 70 %	455300005646
Drying time - First Coat	90 minutes	
Drying time - Second Coat	2-4 days	
Operating Temperature Range	-55 to 150 °C**	
Relative Thermal Index (RTI)	90 °C	UL746B, Table 7.1 Generic Value Based on Composition

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

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*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

INSTRUCTIONS:

1. Bring to room temperature prior to use.
2. Weigh and mix parts A and B accurately and thoroughly, low speed mechanical mixing is preferred taking care not to entrap air and froth the mixture. Scrape sides of container often.
3. Dilute blend as necessary to at viscosity of 16-26 seconds using a #4 Ford Cup for most spray equipment. Xylene is recommended to dilute this product.
4. When a high build thickness is desired use multiple thin coats instead of a few thick coats. This will give better surface finish. Allow to solvent to evaporate between coats.
5. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
6. Clean up uncured resin with suitable organic solvent such as MEK or acetone.

SHELF LIFE AND STORAGE:

12 months at 25 °C.
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.